IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A multi-layer printed wiring board comprising:

a first substrate having an opening and having a plurality of external terminals positioned to be connected to a package substrate;

a second substrate laminated to the first substrate and having a plurality of external terminals positioned to be connected to a mother board, the second substrate having a metallic layer portion in the opening of the first substrate and a plurality of non-through holes filled with conductive material and connected to the metallic layer portion; and

an IC component having a plurality of terminals and loaded in the opening of the first substrate such that the terminals of the IC component face an opposite side of the metallic layer portion of the second substrate ~~with an electronic component and having external terminals, wherein the external terminals are disposed on both faces~~.

Claim 2 (canceled)

Claim 3 (currently amended): The multi-layer printed wiring board according to claim 1, wherein the external ~~terminal~~ terminals of the first substrate are ~~on the opposite face is~~ disposed ~~off just below~~ offset the external ~~terminal on the one face~~ terminals of the second substrate.

Claim 4 (currently amended): The multi-layer printed wiring board according to claim 1, further comprising a plurality of conductive non-through holes provided in the first substrate and connected to the external terminals of the first substrate and a plurality of conductive non-through holes provided in the second substrate and connected to the external terminals of the second substrate, wherein ~~the external terminal is connected to a via hole in stacked structure and the via hole connected to the external terminal is deflected from the via hole in an adjacent layer in terms of their center line~~ the conductive non-through holes in the

first substrate and the conductive non-through holes in the second substrate are positioned offset from each other.

Claim 5 (canceled)

Claim 6 (currently amended): The multi-layer printed wiring board according to claim [[5]] 4, wherein ~~the single side or double side circuit boards are connected to each other through a conductive bump formed on the conductive material filled in the non-through holes~~ the conductive non-through holes in the first and second substrates are provided with a plurality of conductive bumps, respectively.

Claim 7 (currently amended): The [[A]] multi-layer printed wiring board ~~in which a mounted electronic component is wire-bonded from a bonding pad, a substrate being so constructed that a conductor circuit is formed on a single side or double sides of insulation material thereof and the non-through hole leading to the conductor circuit is filled with conductive material, the conductor circuit just above the non-through hole is used as the bonding pad~~ according to claims 1, further comprising a plurality of bonding pads provided for wire bonding the IC component in the first substrate.

Claim 8 (currently amended): The [[A]] multi-layer printed wiring board ~~in which a mounted electronic component is wire-bonded from a bonding pad, a substrate being so constructed that a conductor circuit is formed on a single side or double sides of insulation material thereof and the non-through hole leading to the conductor circuit is filled with conductive material and the conductor circuit just above the non-through hole is used as the bonding pad, while the non-through hole is disposed just below the bonding pad~~ according to claim 7, wherein the plurality of bonding pads are connected to a plurality of conductive non-through holes formed underneath the plurality of bonding pads, respectively.

Claims 9-10 (canceled)

Claim 11 (currently amended): The multi-layer printed wiring board according to claim 7, wherein the bonding ~~pad is formed in~~ pads have a rectangular shape.

Claim 12 (currently amended): The multi-layer printed wiring board according to claim [[9]] 8, wherein the plurality of conductive non-through holes formed underneath the plurality of bonding pads, respectively, has a plurality of [[the]] conductive ~~bump is formed~~ bumps, respectively, on an opposite face [[to]] of the ~~conductor circuit of the~~ bonding [[pad]] pads.

Claims 13-17 (canceled)